



## Material Content Data Sheet



Sales Product Name	TCA785			Issued		28. August 2013		
MA#	MA001043164							
Package	PG-DIP-16-4			Weight*		1031.43 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	6.357	0.62	0.62	6163	6163
leadframe	inorganic material	phosphorus	7723-14-0	0.109	0.01		106	
	non noble metal	zinc	7440-66-6	0.436	0.04		423	
	non noble metal	iron	7439-89-6	8.719	0.85		8453	
	non noble metal	copper	7440-50-8	354.021	34.32	35.22	343233	352215
wire	noble metal	gold	7440-57-5	0.394	0.04	0.04	382	382
encapsulation	organic material	carbon black	1333-86-4	3.216	0.31		3118	
	inorganic material	antimonytrioxide	1309-64-4	12.866	1.25		12474	
	plastics	brominated resin	-	12.866	1.25		12474	
	plastics	epoxy resin	-	131.874	12.79		127855	
	inorganic material	silicondioxide	60676-86-0	482.466	46.77	62.37	467763	623684
leadfinish	non noble metal	tin	7440-31-5	15.796	1.53	1.53	15315	15315
plating	noble metal	silver	7440-22-4	0.358	0.03	0.03	347	347
glue	plastics	epoxy resin	-	0.586	0.06		568	
	noble metal	silver	7440-22-4	1.367	0.13	0.19	1326	1894
*deviation	< 10%	Sum in total:			100,00			1000000

### Important Remarks:

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